This Sheet Has Been Replaced

STACKABLE SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING SAME

ABSTRACT

A stackable semiconductor package having a lead frame, a plurality of electrical paths, and a sealing material. The leadframe has a plurality of leads, each one of the plurality of leads having a top portion exposed to a top surface of the semiconductor package and a bottom portion resting flush with a bottom surface of the semiconductor package. In this manner, the leads extending from the top to the bottom surface of the semiconductor package provide an electrical path for connecting and electrically powering a second semiconductor package stacked on top of a first bottom semiconductor package.